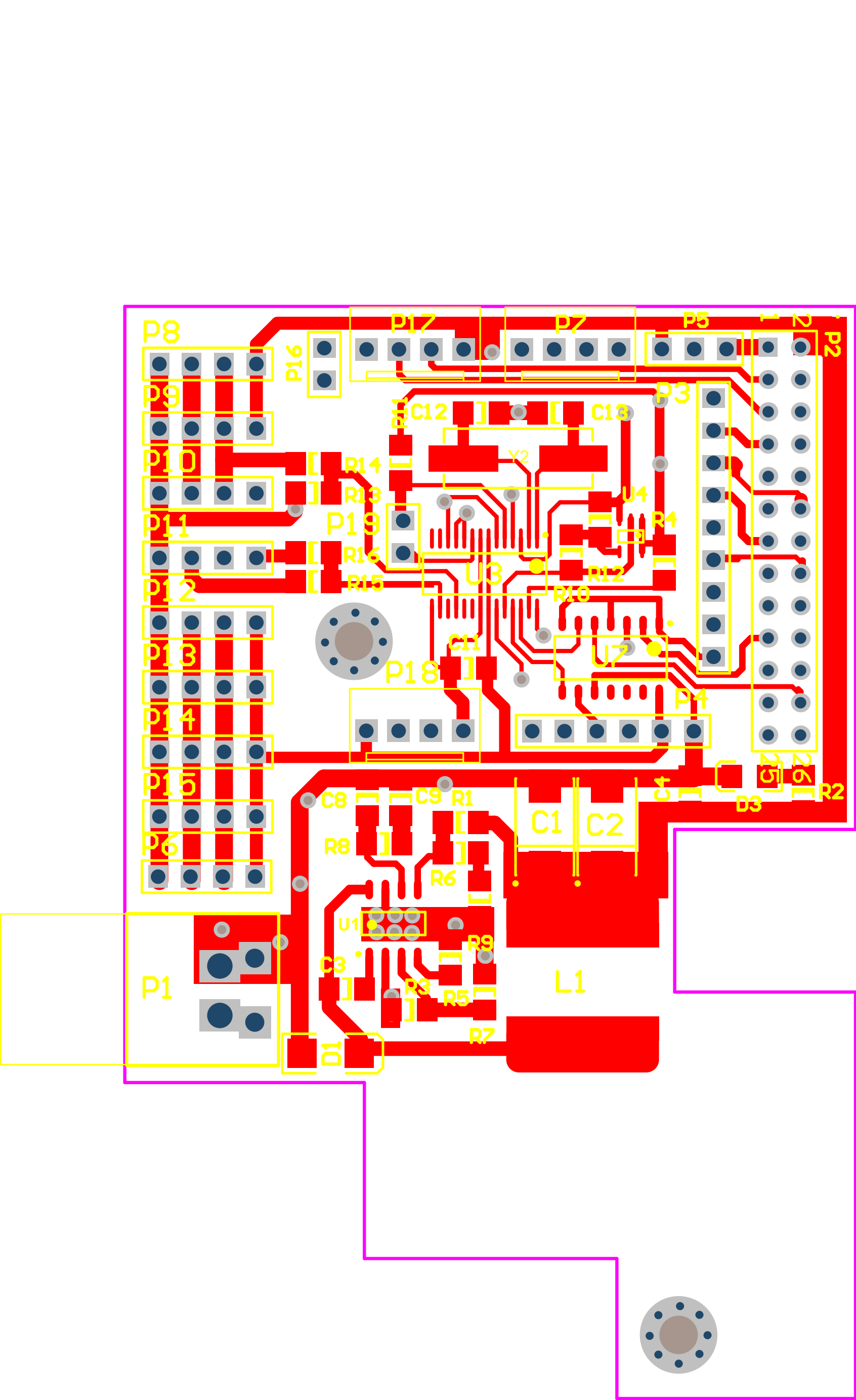
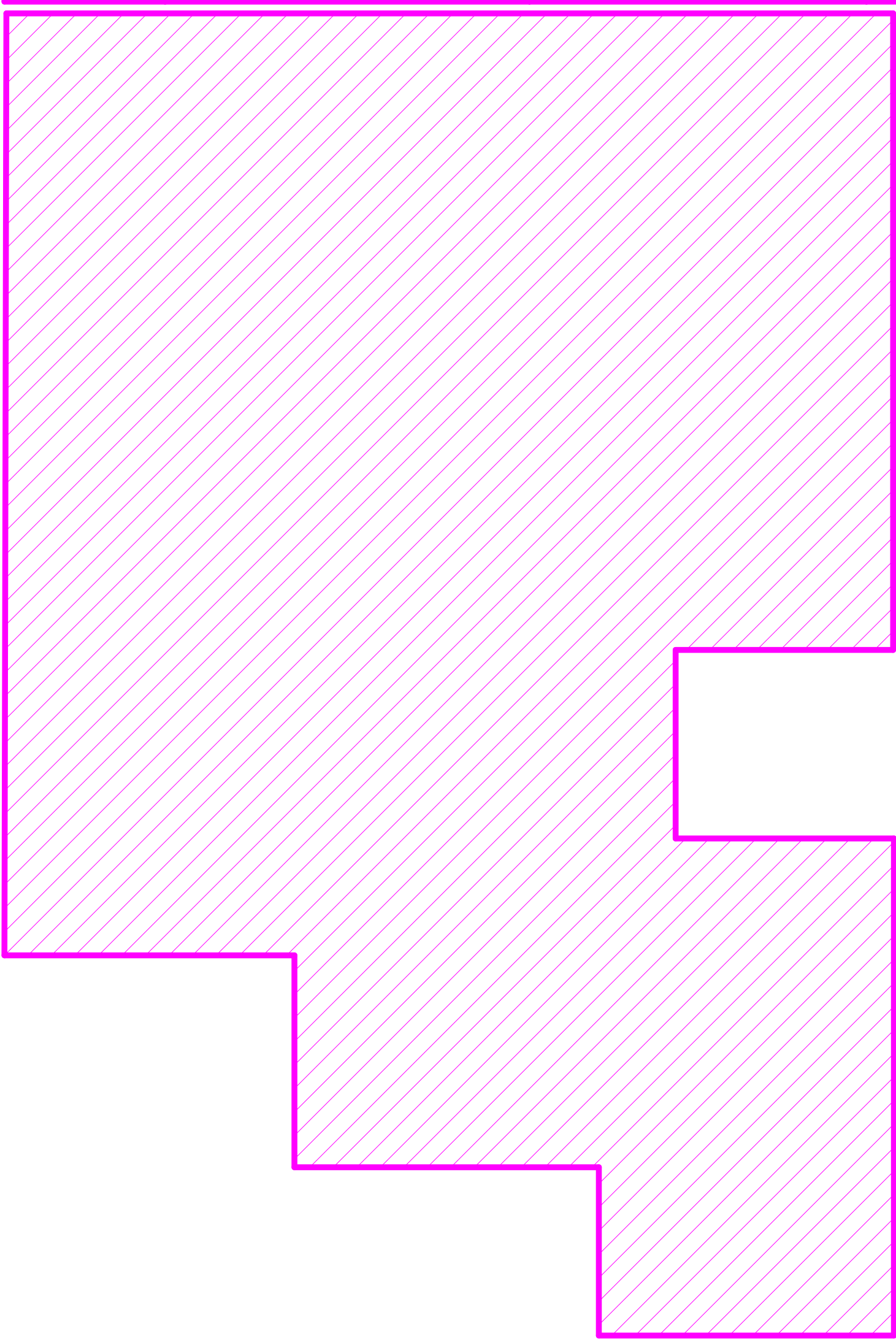


Title			<h1>Robotic-RPI</h1>		
Size	Number			Revision	
A3				v2.0	
Date:	22/01/2019			Sheet of	
File:	C:\Users\...\Robotic-RPI.SchDoc			Drawn By:	



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	12.60mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



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